

MIC4467/8/9

Quad 1.2A Peak Low-Side MOSFET Drivers

Features

- Reliable, Low-Power Bipolar/CMOS/DMOS
 Construction
- Latch-Up Protected to >500 mA Reverse Current
- Logic Input withstands Swing to –5V
- High 3A Peak Output Current
- Wide 4.5V to 18V Operating Range
- Symmetrical Rise and Fall Times
- Short <40 ns Typical Delay Time
- TTL Logic Input Independent of Supply Voltage
- Low Equivalent 6 pF Input Capacitance
- Low 5Ω Typical Output Impedance
- + Output Voltage Swings within 25 mV of Ground or $\rm V_{S}.$

Applications

- General-Purpose CMOS Logic Buffer
- Driving All 4 MOSFETs in an H-Bridge
- Direct Small Motor Driver
- · Relay or Peripheral Drivers
- · Dual Differential Output Power Drivers
- CCD Driver
- · Pin Switching Network Driver

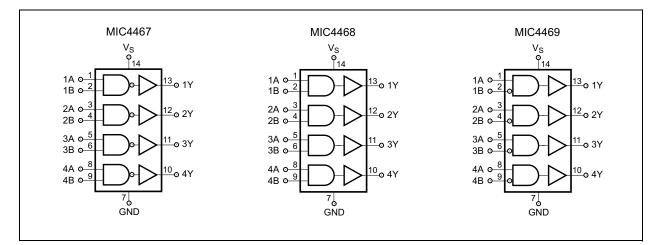
General Description

The MIC4467/8/9 family of four output CMOS buffer/drivers is an expansion from the earlier singleand dual-output drivers, to which they are functionally closely related. Because package pin count permitted it, each driver has been equipped with a dual input logic gate for added flexibility. Placing four high-power drivers in a single package also improves system reliability and reduces total system cost. In some applications, one of these drivers can replace not only two packages of single-input drivers, but some of the associated logic as well.

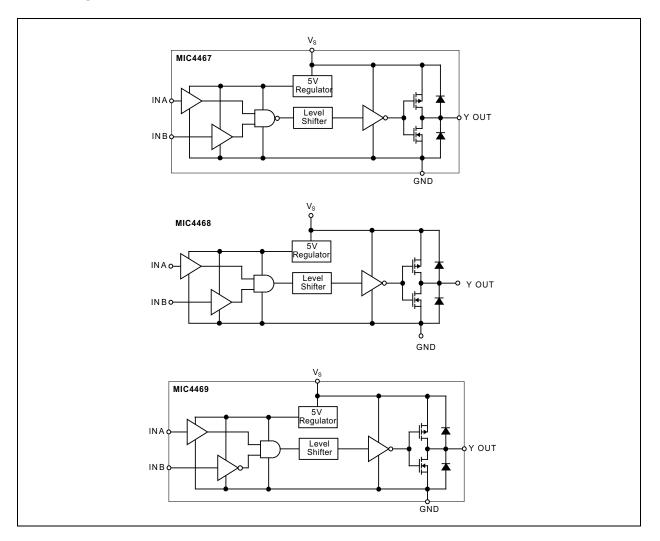
Although primarily intended for driving power MOSFETs, and similar highly capacitive loads, these drivers are equally well suited to driving any other load (capacitive, resistive, or inductive), which requires high efficiency, low-impedance driver capable of high peak currents, rail-to-rail voltage swings, and fast switching times. For example, heavily loaded clock lines, coaxial cables, and piezoelectric transducers can all be driven easily with MIC446x series drivers. The only limitation on loading is that total power dissipation in the IC must be kept within the power dissipation limits of the package.

The MIC446x series drivers are built using a BCD process. They will not latch under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking (either polarity) occurs on the ground line. They can accept up to half an amp of inductive kickback current (either polarity) into their outputs without damage or logic upset.

Logic Diagrams



Block Diagrams



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage	+22V
Input Voltage	V _S + 0.3V to GND – 5V

Operating Ratings ‡

Power Dissipation	
N Package (14-Pin Plastic DIP)	1.5W
WM package (16-Pin Wide SOIC)	1W

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.

‡ Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: Devices are ESD sensitive. Handling precautions are recommended. Human body model, $1.5 \text{ k}\Omega$ in series with 100 pF.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: Measured at $T_A = +25^{\circ}C$ with $4.5V \le V_S \le 18V$ unless otherwise specified. (Note 1)

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Input				•		·
Logic 1 Input Voltage	V _{IH}	2.4	1.3	_	V	—
Logic 0 Input Voltage	V _{IL}	_	1.2	0.8	V	—
Input Current	I _{IN}	-1	_	1	μA	$0V \le V_{IN} \le V_{S}$
Output						
High Output Voltage	V _{OH}	V _S - 0.15		—	V	I _{LOAD} = 10 mA
Low Output Voltage	V _{OL}	—		0.15	V	I _{LOAD} = 10 mA
Output Resistance	R _O	—	5	15	Ω	I _{OUT} = 10 mA, V _S = 18V
Peak Output Current	I _{PK}	—	1.2	—	А	—
Latch-Up Protection Withstand Reverse Current	I	>500	_	_	mA	—
Switching Time						
Rise Time	t _R	—	14	25	ns	Figure 1-1
Fall time	t _F	—	13	25	ns	Figure 1-1
Dolov Timo	t _{D1}	—	30	75	ns	Figure 1-1
Delay Time	t _{D2}	_	45	75	ns	Figure 1-1
Power Supply						
Power Supply Current	ا _S	—	0.2	4	mA	—

Note 1: Specification for packaged product only.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: Measured over operating temperature range with $4.5V \le V_S \le 18V$ unless otherwise specified. (Note 1)

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Input	•		•		•	-
Logic 1 Input Voltage	V _{IH}	2.4	1.4	_	V	—
Logic 0 Input Voltage	V _{IL}	_	1.0	0.8	V	—
Input Current	I _{IN}	-1	—	1	μA	$0V \le V_{IN} \le V_S$
Output						
High Output Voltage	V _{OH}	V _S - 0.3	—	—	V	I _{LOAD} = 10 mA
Low Output Voltage	V _{OL}	-	—	0.3	V	I _{LOAD} = 10 mA
Output Resistance	R _O		7	30	Ω	I _{OUT} = 10 mA, V _S = 18V
Peak Output Current	I _{PK}	_	1.2	-	А	—
Latch-Up Protection Withstand Reverse Current	I	500	—	—	mA	—
Switching Time				•		
Rise Time	t _R		17	50	ns	Figure 1-1
Fall time	t _F	_	16	50	ns	Figure 1-1
Dolov Timo	t _{D1}	_	35	100	ns	Figure 1-1
Delay Time	t _{D2}	-	55	100	ns	Figure 1-1
Power Supply						
Power Supply Current	۱ _S	_	0.4	8	mA	—
Power Supply Current Note 1: Specification for pac	-	— luct only.	0.4	8	mA	

Note 1: Specification for packaged product only.

TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
On anotine dankie of Tanan anotana	т	-40	_	+85	°C	Temperature Range Device: Y
Operating Ambient Temperature	T _A	0	_	+70	°C	Temperature Range Device: Z
Maximum Junction Temperature	TJ	_	_	+150	°C	—
Storage Temperature Range	Τ _S	-65	_	+150	°C	—
Lead Temperature	T _{LEAD}	_	_	+300	°C	Soldering, 10 sec.
Package Thermal Resistances						
Thermal Resistance 14-Lead PDIP	θ_{JA}	_	80	_	°C/W	—
Thermal Resistance 16-Lead Wide SOIC	θ_{JA}	_	120	_		—

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}).

Test Circuits

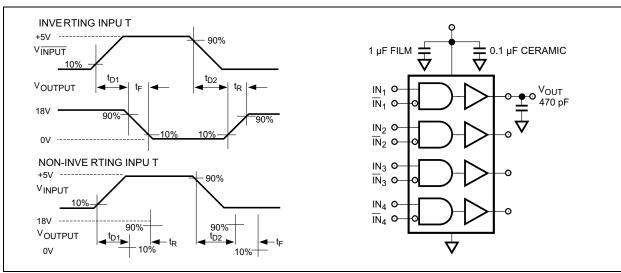


FIGURE 1-1:

Inverting and Non-Inverting Input.

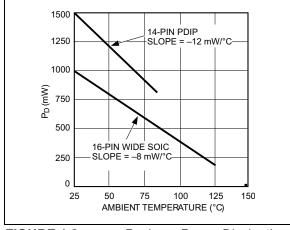


FIGURE 1-2:

Package Power Dissipation.

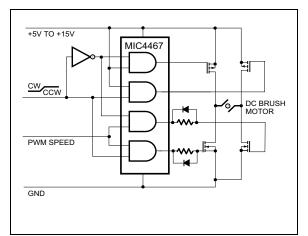
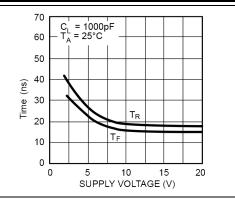
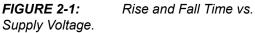


FIGURE 1-3: Quad Driver Drives H Bridge to Control motor Speed and Direction.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.





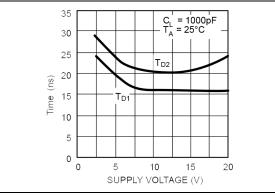
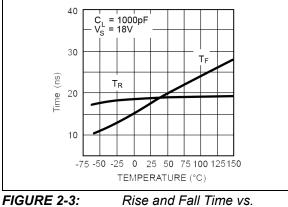


FIGURE 2-2: Delay Time vs. Supply Voltage.



Temperature.

ise and Fall Time V

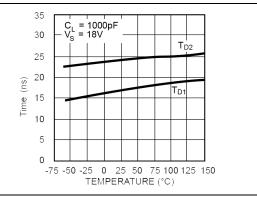


FIGURE 2-4: Delay Time vs. Temperature.

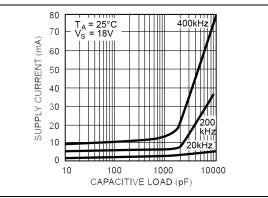


FIGURE 2-5: Supply Current vs. Capacitive Load.

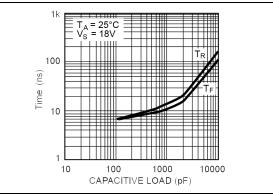


FIGURE 2-6:Rise and Fall Time vs.Capacitive Load.

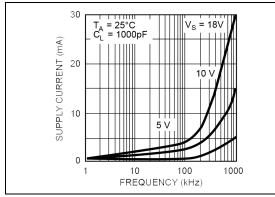


FIGURE 2-7: Supply Current vs. Frequency.

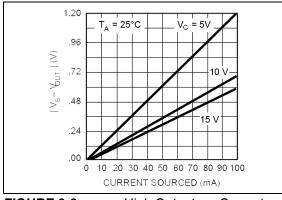


FIGURE 2-8:

High Output vs. Current.

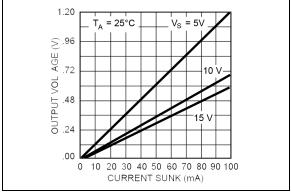


FIGURE 2-9:

Low Output vs. Current.

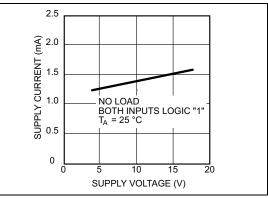


FIGURE 2-10: Quiescent Power Supply Current vs. Supply Voltage.

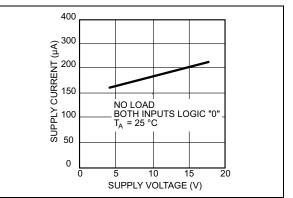
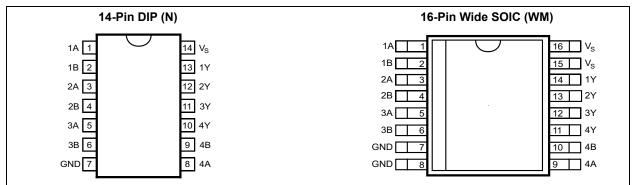


FIGURE 2-11:Quiescent Power SupplyCurrent vs. Supply Voltage.

3.0 PIN DESCRIPTIONS

Package Types



The descriptions of the pins are listed in Table 3-1.

TABLE 3-1:PIN FUNCTION TABLE

Pin Number DIP	Pin Number Wide SOIC	Pin Name	Description			
1	1	1A	Input A for Driver 1. TTL/CMOS Compatible Input			
2	2	1B	Input B for Driver 1. TTL/CMOS Compatible Input			
3	3	2A	Input A for Driver 2. TTL/CMOS Compatible Input			
4	4	2B	Input B for Driver 2. TTL/CMOS Compatible Input			
5	5	3A	Input A for Driver 3. TTL/CMOS Compatible Input			
6	6	3B	Input B for Driver 3. TTL/CMOS Compatible Input			
7	7	GND	Ground			
8	_	4A	Input A for Driver 4. TTL/CMOS Compatible Input			
—	8	GND	Ground			
9	_	4B	Input B for Driver 4. TTL/CMOS Compatible Input			
—	9	4A	Input A for Driver 4. TTL/CMOS Compatible Input			
10	_	4Y	Output for Driver 4, CMOS Push-Pull Output			
—	10	4B	Input B for Driver 4. TTL/CMOS Compatible Input			
11	—	3Y	Output for Driver 3, CMOS Push-Pull Output			
—	11	4Y	Output for Driver 4, CMOS Push-Pull Output			
12	_	2Y	Output for Driver 2, CMOS Push-Pull Output			
—	12	3Y	Output for Driver 3, CMOS Push-Pull Output			
13	_	1Y	Output for Driver 1, CMOS Push-Pull Output			
	13	2Y	Output for Driver 2, CMOS Push-Pull Output			
14	_	VS	Supply Input, 4.5V to 18V			
	14	1Y	Output for Driver 1, CMOS Push-Pull Output			
	15	VS	Supply Input, 4.5V to 18V			
—	16	VS	Supply Input, 4.5V to 18V			

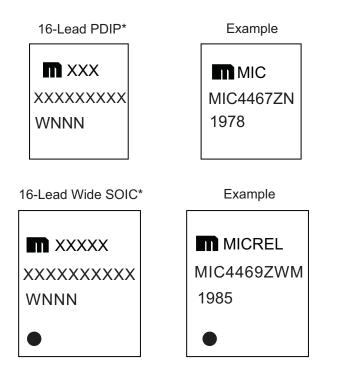
3.1 Truth Table

TABLE 3-2: TRUTH TABLE

Dort No.	Inp	Output	
Part No.	Α	В	Y
NUO 4407	L	Х	Н
MIC4467 (Each Driver)	Х	L	Н
	Н	Н	L
N/10/1/00	Н	Н	Н
MIC4468 (Each Driver)	L	Х	L
	Х	L	L
MIC4469 (Each Driver)	L	Х	L
	Х	Н	L
	Н	L	Н

4.0 PACKAGING INFORMATION

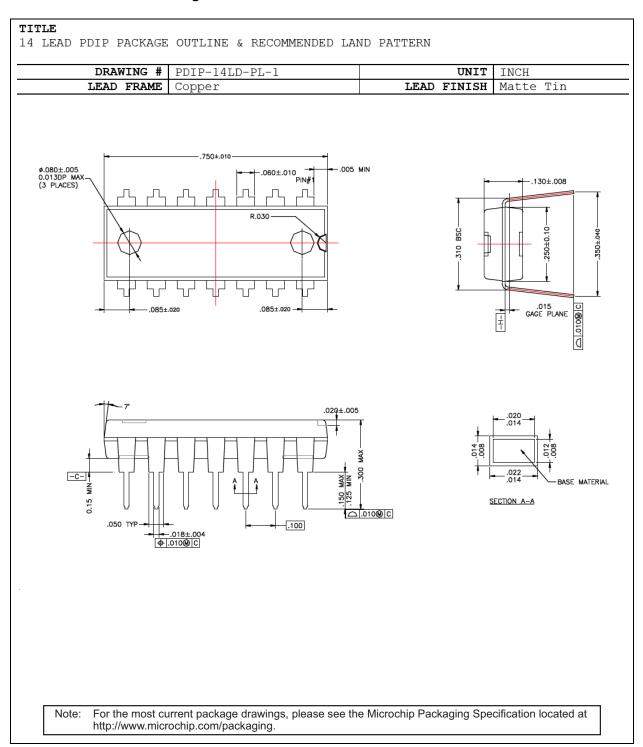
4.1 Package Marking Information



Legend:	Y YY WW NNN @3 *	Product code or customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package. Pin one index is identified by a dot, delta up, or delta down (triangle
b c tł	e carriec haracters he corpor	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available for customer-specific information. Package may or may not include ate logo. (_) and/or Overbar (⁻) symbol may not be to scale.

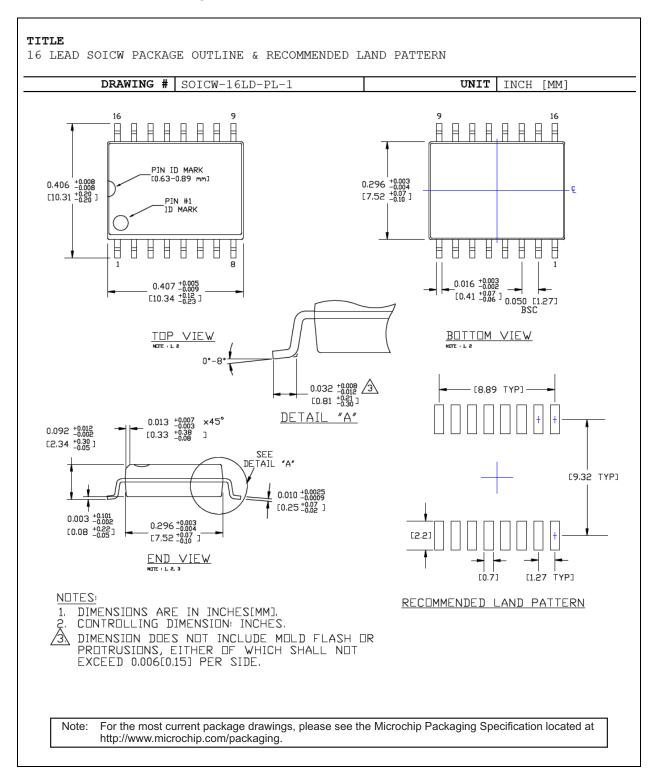
Note: If the full seven-character YYWWNNN code cannot fit on the package, the following truncated codes are used based on the available marking space:

6 Characters = YWWNNN; 5 Characters = WWNNN; 4 Characters = WNNN; 3 Characters = NNN; 2 Characters = NN; 1 Character = N



14-Lead Plastic DIP Package Outline and Recommended Land Pattern

16-Lead Wide SOIC Package Outline and Recommended Land Pattern



APPENDIX A: REVISION HISTORY

Revision A (May 2022)

- Converted Micrel document MIC4467/8/9 to Microchip data sheet DS20006614A.
- Minor text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

	Y	XX	-XX	Example	es:	
PART NO.	X Temperature Range	e Package	 │ Media Type	a) MIC446	7:	1.2A-Peak, Quad Low-Side MOSFET Driver, NAND Input Logic, –40°C to +85°C Industrial Temperature Range, RoHS Compliant
				MIC4467Y	WM	16-Lead SOIC Wide Package, 47/Tube
	MIC4467:	Quad 1.2A-Peak Low	-Side MOSFET Driver	MIC4467Y	WM-TR	16-Lead SOIC Wide Package, 1,000/Reel
		with Bi-Polar/CMOS/I ing NAND Input Logic	DMOS Process featur-	b) MIC446	7:	1.2A-Peak, Quad Low-Side MOSFET Driver, NAND Input Logic, 0°C to +70°C Commercial Temperature Range, RoHS Compliant
Device:		with Bi-Polar/CMOS/I		MIC4467Z	N	14-Lead PDIP Package, 25/Tube
		featuring AND Input L	eaturing AND Input Logic	MIC4467Z	WM	16-Lead SOIC Wide Package, 47/Tube
	MIC4469:	Quad 1.2A-Peak Low	-Side MOSFET Driver	MIC4467Z	WM-TR	16-Lead SOIC Wide Package, 1000/Reel
		with Bi-Polar/CMOS/I featuring AND with 1		c) MIC446	8:	1.2A-Peak, Quad Low-Side MOSFET Driver, AND Input Logic, –40°C to +85°C Industrial Temperature Range, RoHS Compliant
Temperature Range	: Y =	-40°C to +85°C, Indu	strial	MIC4468Y	N	14-Lead PDIP Package, 25/Tube
	Z =	(RoHs Compliant) 0°C to +70°C, Comme	ercial	MIC4468Y	WM	16-Lead SOIC Wide Package, 47/Tube
	-	(RoHs Compliant)		MIC4468Y	WM-TR	16-Lead SOIC Wide Package, 1,000/Reel
Package:	N = WM =	14-Lead PDIP 16-Lead SOIC (Wide	Body)	d) MIC446	8:	1.2A-Peak, Quad Low-Side MOSFET Driver, AND Input Logic, 0°C to +70°C Commercial Temperature Range, RoHS Compliant
				MIC4468Z	N	14-Lead PDIP Package, 25/Tube
Media Type:	<blank> =</blank>	25/Tube (N, PDIP)		MIC4468Z	WM	16-Lead SOIC Wide Package, 47/Tube
	<blank> = 47/Tube (</blank>	47/Tube (WM, SOIC)		MIC4468Z	WM-TR	16-Lead SOIC Wide Package, 1,000/Reel
		1,000/Reel (WM, SOI	,000/Reel (WM, SOIC) MIC4469:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND with 1 Inverting Input Logic, –40°C to +85°C Industrial Temperature Range, RoHS Compliant	
				MIC4469Y	'N	14-Lead PDIP Package, 25/Tube
				MIC4469Y	WM	16-Lead SOIC Wide Package, 47/Tube
				MIC4469Y	WM-TR	16-Lead SOIC Wide Package, 1,000/Reel
				MIC4469:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND with 1 Inverting Input Logic, –40°C to +85°C Commercial Temperature Range, RoHS Compliant
				MIC4469Z	N	14-Lead PDIP Package, 25/Tube
				MIC4469Z	WM	16-Lead SOIC Wide Package, 47/Tube
				MIC4469W	/M-TR	16-Lead SOIC Wide Package, 1,000/Reel
				Note 1:	part numl ordering package.	Reel identifier only appears in the catalog ber description. This identifier is used for purposes and is not printed on the device Check with your Microchip Sales Office for availability with the Tape and Reel option.

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